

## 1500W, 12V - 51V Surface Mount Transient Voltage Suppressor

### FEATURES

- AEC-Q101 qualified
- Moisture sensitivity level: level 1, per J-STD-020
- Meets IEC 61000-4-2 (Level: 4) / ISO 10605 (Level: L4)
- Meets ISO7637-2 (Pulse 1/2a/2b/3a/3b)
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

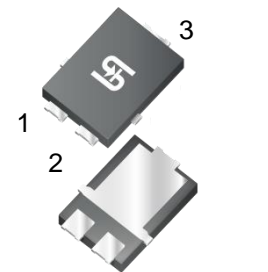
### APPLICATIONS

- Switching mode power supply (SMPS)
- Motor for BLDC
- Lighting application
- Battery Management System
- Automotive

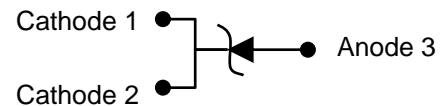
### MECHANICAL DATA

- Case: TO-277A (SMPC4.6U)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Uni-directional
- Weight: 0.095g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$V_{WM}$	10.2 - 43.6	V
$V_{BR}$	12 - 51	V
$P_{PPM}$	1500	W
$T_{JMAX}$	175	°C
Polarity	Uni-directional	
Package	TO-277A (SMPC4.6U)	



TO-277A (SMPC4.6U)



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNIT
Non-repetitive peak impulse power dissipation with 10/1000 $\mu\text{s}$ waveform <sup>(1)</sup>	$P_{PPM}$	1500	W
Peak forward surge current 8.3ms single half sine-wave	$I_{FSM}$	200	A
Junction temperature	$T_J$	-55 to +175	°C
Storage temperature	$T_{STG}$	-55 to +175	°C

#### Notes:

1. Non-repetitive current pulse per Fig.3 and derated above  $T_A = 25^\circ\text{C}$  per Fig.1

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	6.4	°C/W
Junction-to-ambient thermal resistance	$R_{\theta JA}$	51.1	°C/W
Junction-to-case thermal resistance	$R_{\theta JC}$	8.9	°C/W

**Thermal Performance Note:** Units mounted on PCB (16mm x 16mm Cu pad test board)

## ELECTRICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)

PART NUMBER	DEVICE MARKING CODE	BREAKDOWN VOLTAGE $V_{BR}^{(1)}$ AT $I_T$ (V)			TEST CURRENT $I_T$ (mA)	STAND-OFF VOLTAGE $V_{WM}$ (V)	MAXIMUM REVERSE LEAKAGE AT $V_{WM}$ $I_R$ ( $\mu\text{A}$ )	MAXIMUM REVERSE LEAKAGE AT $V_{WM}$ $T_J = 150\text{ }^\circ\text{C}$ $I_b$ ( $\mu\text{A}$ )	MAXIMUM PEAK PULSE SURGE CURRENT $I_{PPM}^{(2)}$ (A)	MAXIMUM CLAMPING VOLTAGE AT $I_{PPM}$ $V_c$ (V)	TYPICAL TEMP. COEFFICIENT OF $V_{BR}^{(3)}$ $\alpha_T$ (%/°C)
		MIN	NOM	MAX							
1K5SMPC12APH	SMPC12AP	11.4	12.0	12.6	1.0	10.2	2.0	10	89.8	16.7	0.070
1K5SMPC13APH	SMPC13AP	12.4	13.0	13.7	1.0	11.1	2.0	10	82.4	18.2	0.072
1K5SMPC15APH	SMPC15AP	14.3	15.0	15.8	1.0	12.8	1.0	10	70.8	21.2	0.076
1K5SMPC16APH	SMPC16AP	15.2	16.0	16.8	1.0	13.6	1.0	10	66.7	22.5	0.078
1K5SMPC18APH	SMPC18AP	17.1	18.0	18.9	1.0	15.3	1.0	10	59.5	25.2	0.080
1K5SMPC20APH	SMPC20AP	19.0	20.0	21.0	1.0	17.1	1.0	10	54.2	27.7	0.082
1K5SMPC22APH	SMPC22AP	20.9	22.0	23.1	1.0	18.8	1.0	10	49.0	30.6	0.084
1K5SMPC24APH	SMPC24AP	22.8	24.0	25.2	1.0	20.5	1.0	10	45.2	33.2	0.085
1K5SMPC27APH	SMPC27AP	25.7	27.0	28.4	1.0	23.1	1.0	10	40.0	37.5	0.087
1K5SMPC30APH	SMPC30AP	28.5	30.0	31.5	1.0	25.6	1.0	10	36.2	41.4	0.088
1K5SMPC33APH	SMPC33AP	31.4	33.0	34.7	1.0	28.2	1.0	10	32.8	45.7	0.089
1K5SMPC36APH	SMPC36AP	34.2	36.0	37.8	1.0	30.8	1.0	15	30.1	49.9	0.090
1K5SMPC39APH	SMPC39AP	37.1	39.0	41.0	1.0	33.3	1.0	15	27.8	53.9	0.091
1K5SMPC43APH	SMPC43AP	40.9	43.0	45.2	1.0	36.8	1.0	20	25.3	59.3	0.092
1K5SMPC47APH	SMPC47AP	44.7	47.0	49.4	1.0	40.2	1.0	20	23.1	64.8	0.092
1K5SMPC51APH	SMPC51AP	48.5	51.0	53.6	1.0	43.6	1.0	20	21.4	70.1	0.093

**Notes:**

1. Pulse test with  $PW = 30\text{ms}$
2. Surge current waveform per Fig.3 and derated per Fig.1
3. To calculate  $V_{BR}$  vs. junction temperature, use the following formula:  $V_{BR}$  at  $T_J = V_{BR}$  at  $25\text{ }^\circ\text{C} \times (1 + \alpha_T \times (T_J - 25))$

ORDERING INFORMATION		
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
1K5SMPCxAPH	TO-277A (SMPC4.6U)	6,000/ Tape & Reel

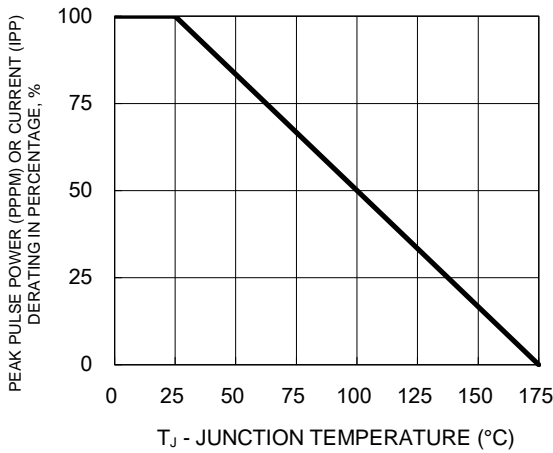
**Notes:**

1. "x" defines voltage from 12V (1K5SMPC12APH) to 51V (1K5SMPC51APH)

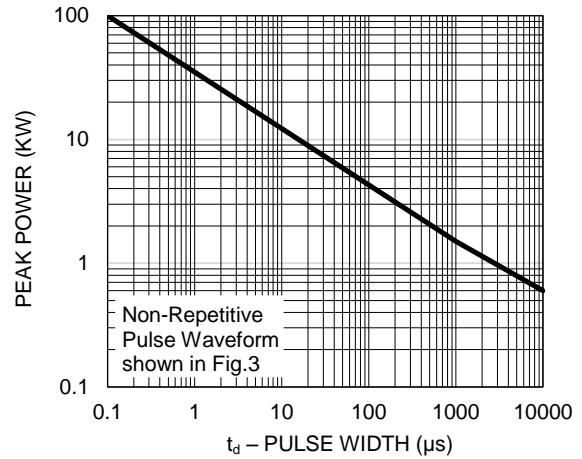
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

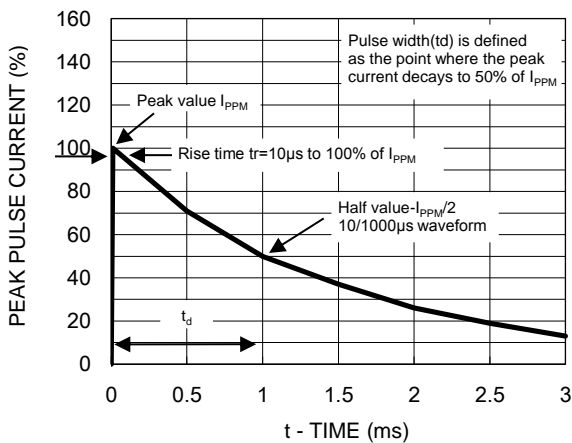
**Fig.1 Pulse Power or Current vs. Junction Temperature**



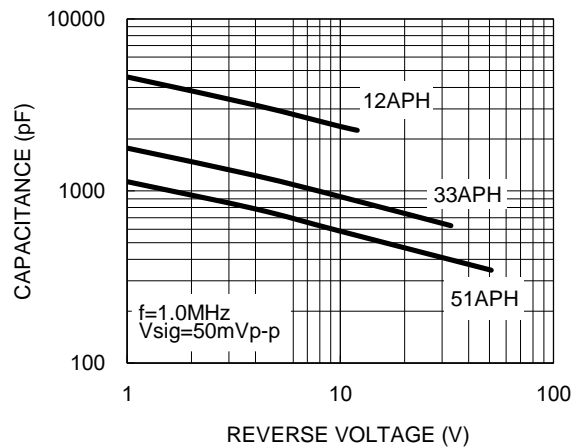
**Fig.2 Peak Pulse Power Rating Curve**



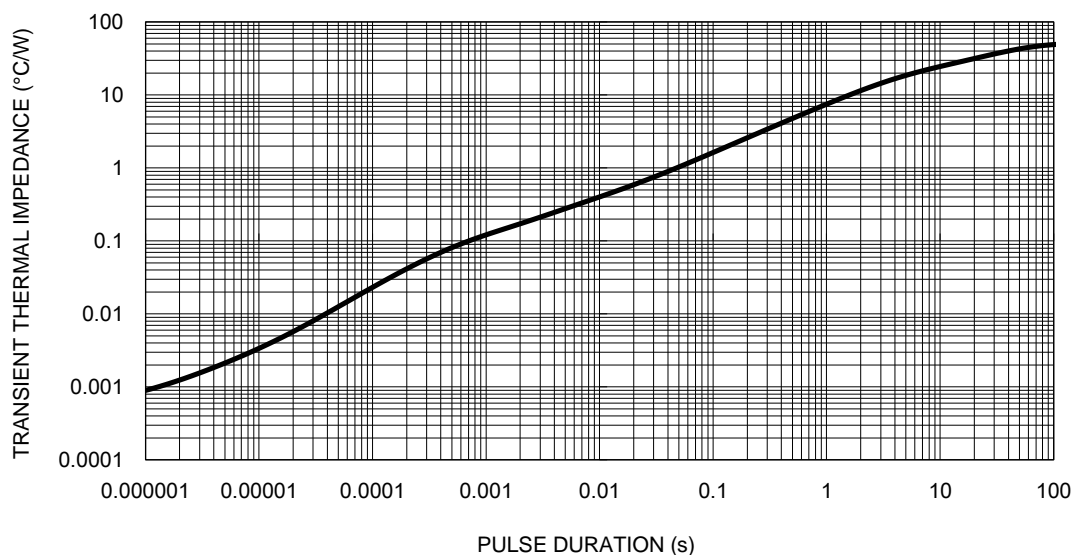
**Fig.3 Clamping Power Pulse Waveform**



**Fig.4 Typical Junction Capacitance**

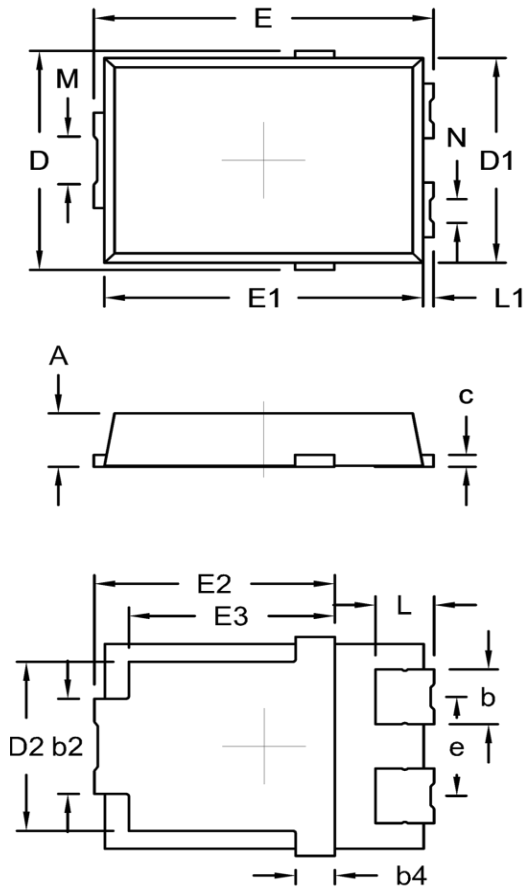


**Fig.5 Typical Transient Thermal Impedance**



## PACKAGE OUTLINE DIMENSIONS

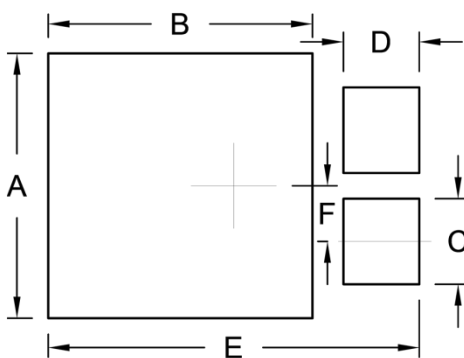
TO-277A (SMPC4.6U)



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	1.00	1.20	0.039	0.047
b	1.05	1.35	0.041	0.053
b2	1.90	2.20	0.075	0.087
b4	0.75 (NOM.)		0.030 (NOM.)	
c	0.15	0.40	0.006	0.016
D	4.45	4.75	0.175	0.187
D1	4.25	4.35	0.167	0.171
D2	3.40	3.70	0.134	0.146
E	6.35	6.65	0.250	0.262
E1	6.05	6.15	0.238	0.242
E2	4.40	4.80	0.173	0.189
E3	3.94 (NOM.)		0.155 (NOM.)	
e	2.08 (NOM.)		0.082 (NOM.)	
L	0.94	1.24	0.037	0.049
L1	0.05	0.35	0.002	0.014
M	0.65	1.15	0.026	0.045
N	0.25	0.75	0.010	0.030

Package body size D1 and E1 do not include mold flash  
Mold flash shall not exceed 0.1mm per side

## SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	4.95	0.195
B	4.95	0.195
C	1.60	0.063
D	1.42	0.056
E	6.95	0.274
F	1.04	0.041

## MARKING DIAGRAM



P/N = Marking Code  
YW = Date Code  
F = Factory Code